



GENERAL DESCRIPTION

EM58000 is a series of single chip dual channel IC with voice synthesizer/dual tone melody/dual tone sound effect. The dual channel can be (voice + voice), (voice + dual tone melody) or (voice + dual tone sound effect) simultaneously. That contains some input and I/O ports, and a tiny controller. By programming through the tiny controller, user's application including section combination, trigger modes, control outputs, IR communication, and other logical function can be easily implemented.

FEATURES

	EM58001	EM58101	EM58200	EM58300	EM58400	EM58500	EM58600	EM58700
TOTAL ROM(bits)	10K x 10	16K x 10	32K x 10	64K x 10	128K x 10	256K x 10	512K x 10	1024K x 10
PROGRAMROM(bits)	8K x 10		32K x 10					
RAM(nibbles)	32	64	128					
PORT1 [input](pins)	-		4					
PORT2 [I/O](pins)	2	4						
PORT3 [I/O](pins)	4							
VO(pins)	1		2					

- Single power supply 2.4 V~ 5.5 V.
- Port1 and Port2 with wake-up function, Port3.2 with programmable IR (38 KHz carry) communication function.
- Power down mode for saving power consumption.
- Single ROM for voice, melody, sound effect and program data.
- Readable ROM code data.
- One 6-bit timer overflow control.
- Two stacks for subroutine calling.
- Dual channel output simultaneously : (voice + voice), (voice + dual tone melody) or (voice + dual tone sound effect).
- 5-bit ASPCM synthesizer.
- Dual tone melody/sound effect generator with programmable envelope.
- Multiple playing speeds in 2 KHz ~ 32 KHz for voice playback.
- Multiple tempos and variable beats for dual tone melody/sound effect playback.
- Multiple levels of volume control.
- Fixed current D/A to drive external connected transistor for audio output.

PIN DESCRIPTIONS

Symbol	I/O	Function
P1.0	I	Bit 0 of Port 1. (not for EM58001, EM58101)
P1.1	I	Bit 1 of Port 1. (not for EM58001, EM58101)
P1.2	I	Bit 2 of Port 1. (not for EM58001, EM58101)
P1.3	I	Bit 3 of Port 1. (not for EM58001, EM58101)
P2.0	I/O	Bit 0 of Port 2. (not for EM58001)
P2.1	I/O	Bit 1 of Port 2. (not for EM58001)
P2.2	I/O	Bit 2 of Port 2.
P2.3	I/O	Bit 3 of Port 2.
P3.0	I/O	Bit 0 of Port 3.
P3.1	I/O	Bit 1 of Port 3.
P3.2	I/O	Bit 2 of Port 3. The pin can generate 38KHz square wave.
P3.3	I/O	Bit 3 of Port 3. The pin can be treated as an LED output flashing with volume.
VDD	I	Positive power supply.
OSC	I	Oscillation component connection pin.
VSS	I	Negative power supply.
VO1	O	Audio1 output.
VO2	O	Audio2 output. (not for EM58001, EM58101)
TEST		For testing only

ABSOLUTE MAXIMUM RATINGS

Items	Sym.	Min.	Max.	Unit
Supply Voltage	$V_{DD} - V_{SS}$	-0.3	6.0	V
Input Voltage	V_{IN}	$V_{SS} - 0.3$	$V_{DD} + 0.3$	V
Operating Temperature	T_{OP}	-20	70	°C
Storage Temperature	T_{STG}	-55	+125	°C

ELECTRICAL CHARACTERISTICS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Condition
Operating voltage	V_{DD}	2.4	3.0	5.5	V	
Standby current	I_{DDS}	-	-	1.0	μA	$V_{DD}=3V$
Operating current	I_{DDO}	-	-	250	μA	$V_{DD}=3V$, No load
Drive current of P2,P3	I_{OD}	2.0	3.0	-	mA	$V_{DD}=3V$, $V_O=2.4V$
Sink current of P3	I_{OS}	2.3	3.5	-	mA	$V_{DD}=3V$, $V_O=0.4V$

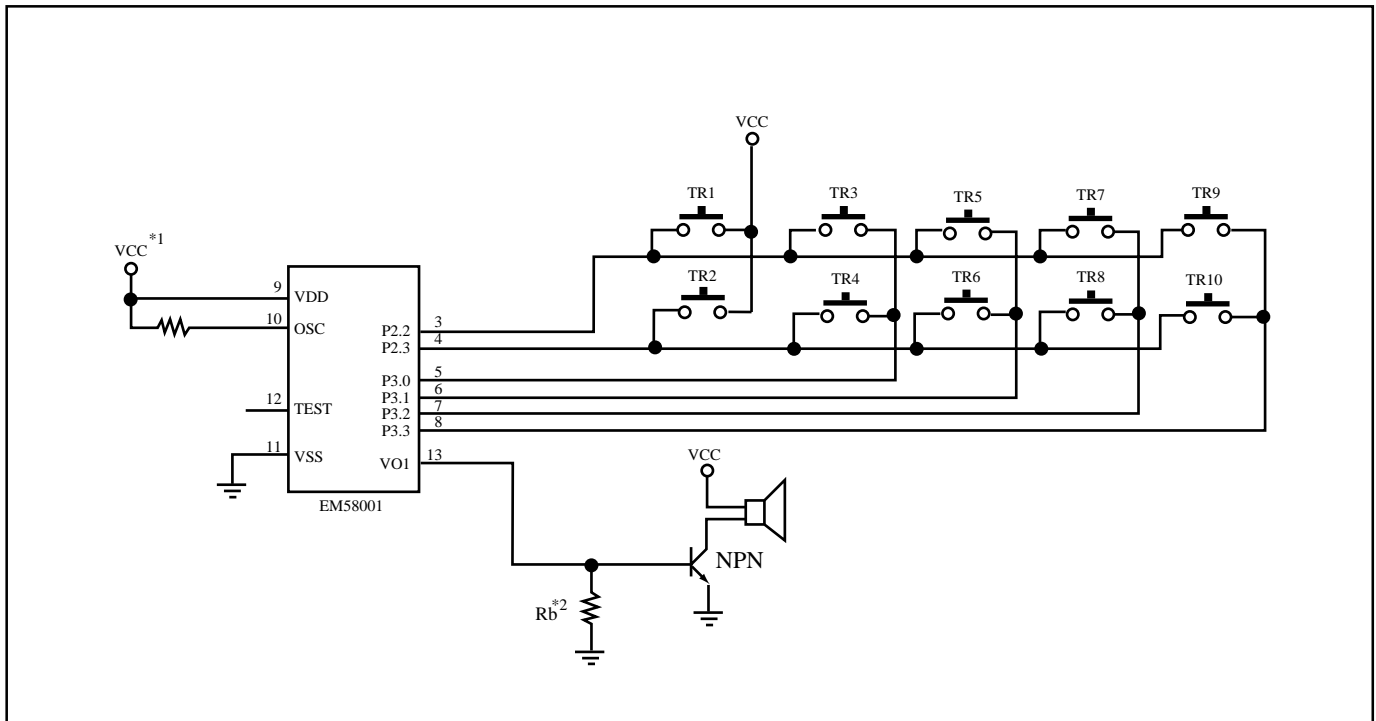
Parameter	Sym.	Min.	Typ.	Max.	Unit	Condition
Sink current of P2 (after KEYB)	I_{OS1}	2.3	3.5	-	mA	$V_{DD}=3V, V_O=0.4V$
Sink current of P2 (before KEYB)	I_{OS2}	-	3.0	10	μA	$V_{DD}=3V, V_O=0.4V$
Input current of P1	I_{IH}	-	3.0	10	μA	$V_{DD}=3V$
Output current of VO1, VO2	I_{VO}	4.0	5.0	6.0	mA	$V_{DD}=3V, V_O=0.7V,$ two channel full scale output
Oscillation resistor	R_{OSC}	-	470	-	K Ω	$V_{DD}=2.4V \sim 5.5V$
Oscillation frequency	F_{OSC}	0.9	1.0	1.1	MHz	$V_{DD}=2.4V \sim 5.5V$
Oscillation frequency deviation	$\frac{\Delta F_{OSC}}{F_{OSC}}$	-10	0	10	%	$V_{DD}=2.4V \sim 5.5V$

APPLICATION CIRCUIT

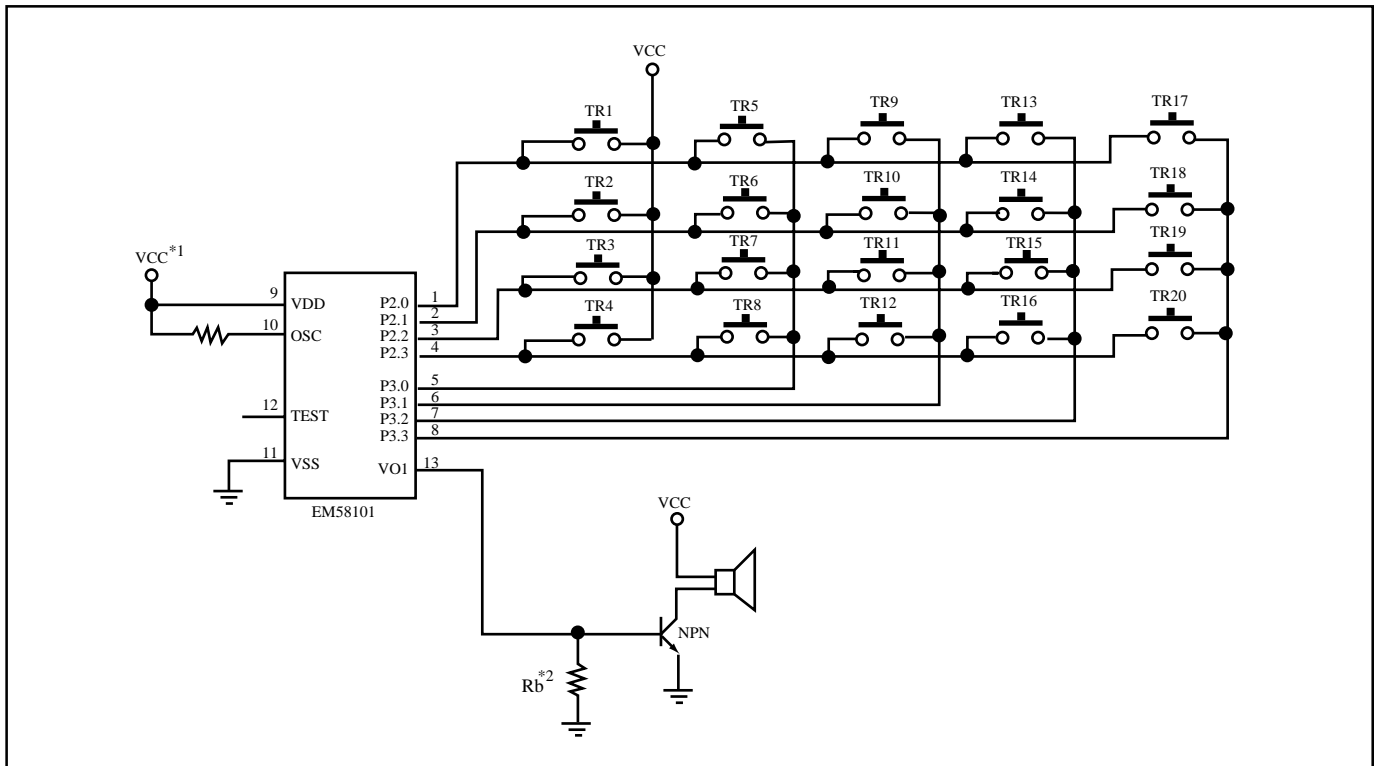
In the following application circuits:

- *1 : For heavy loading application, adding an electrolytic capacitor between Vcc and Ground is recommended.
The recommended value for button cell application is 10 μF .
- *2 : The recommended value for button cell application is 750 Ω or less.

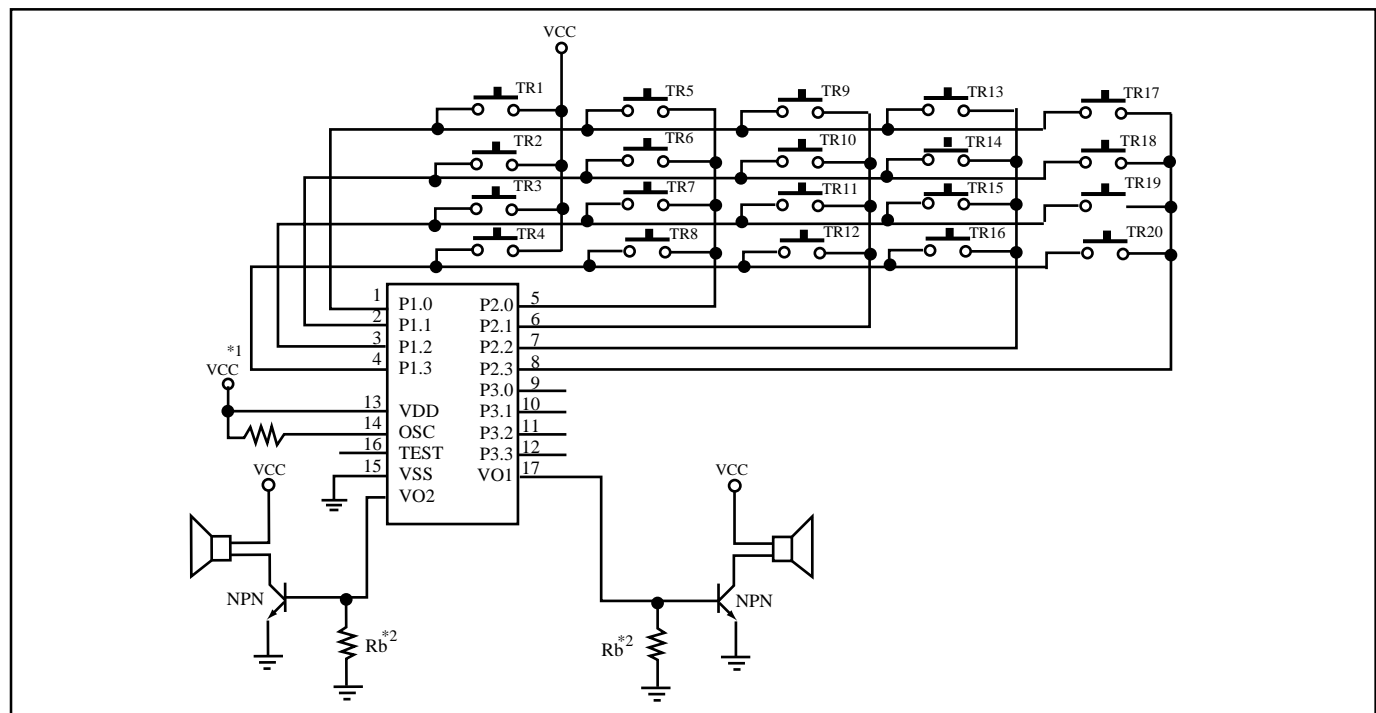
10-key Application Circuit For EM58001



20-key Application Circuit For EM58101

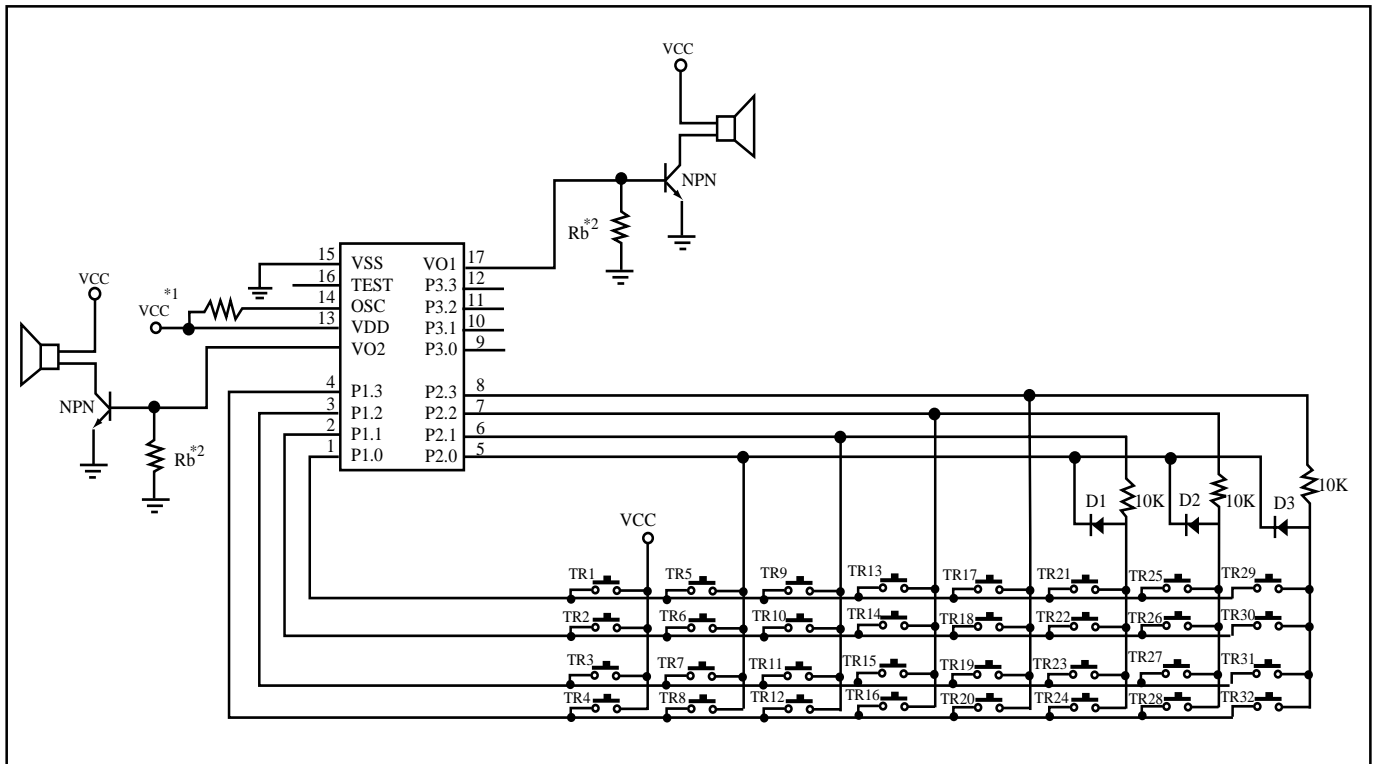


20-key Application Circuit For EM58200~EM58700

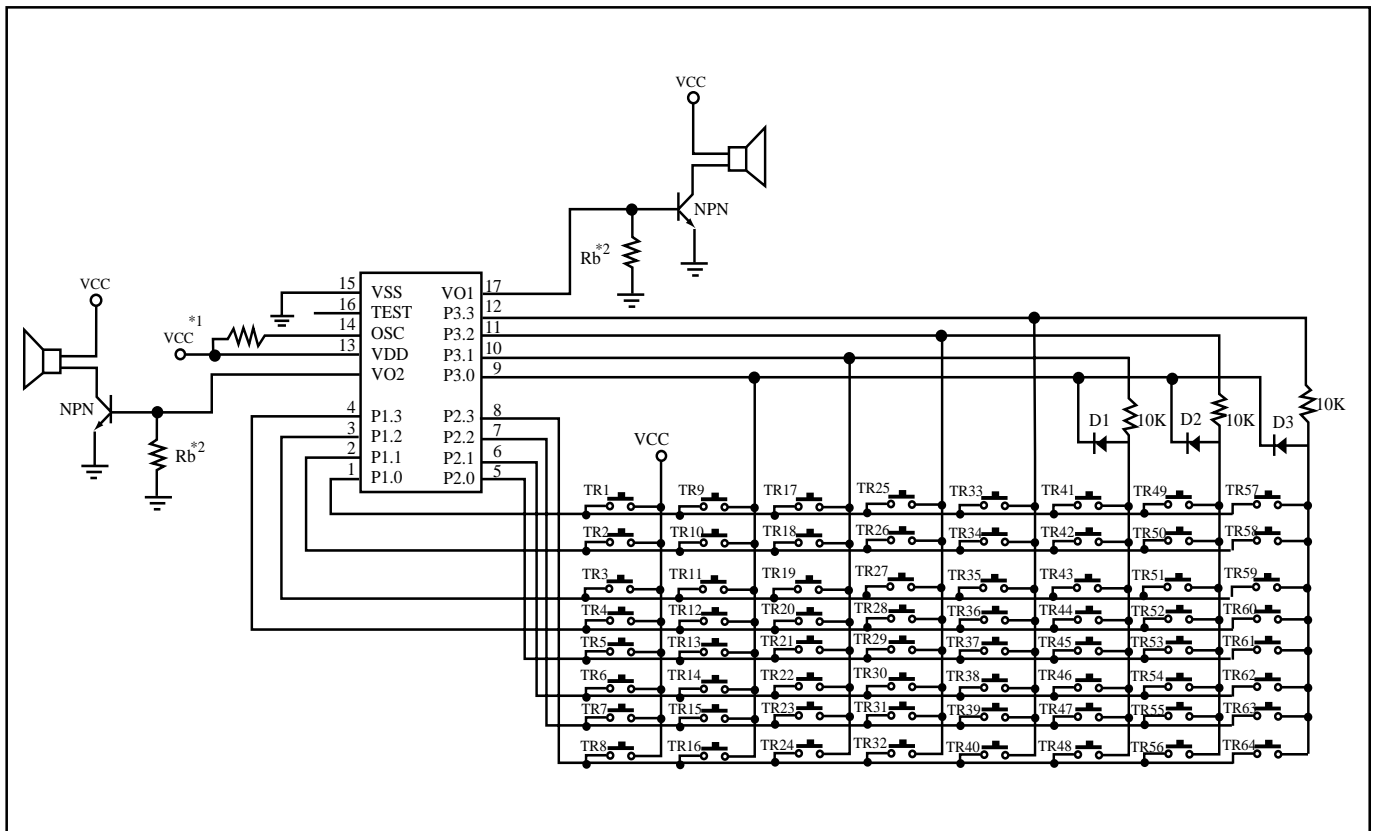


* This specification are subject to be changed without notice.

32-key Application Circuit For EM58200~EM58700

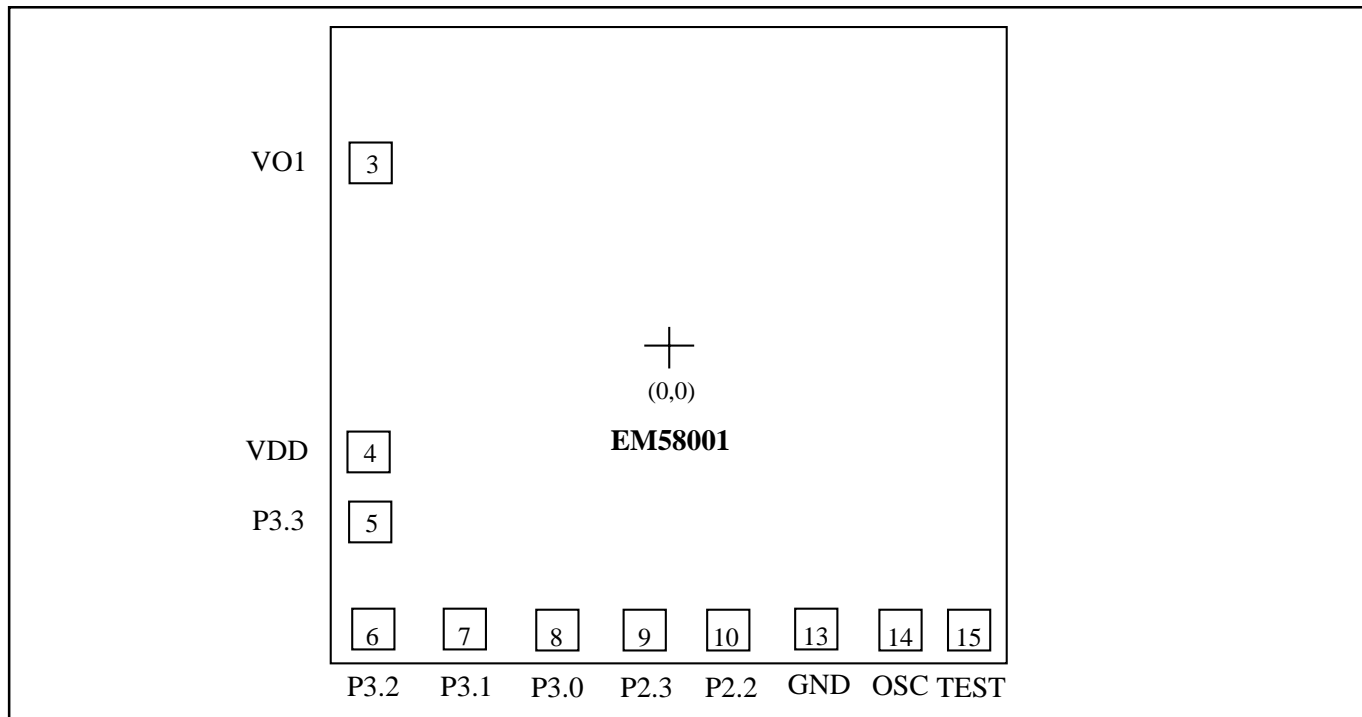


64-key Application Circuit For EM58200~EM58700



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PAD DIAGRAM

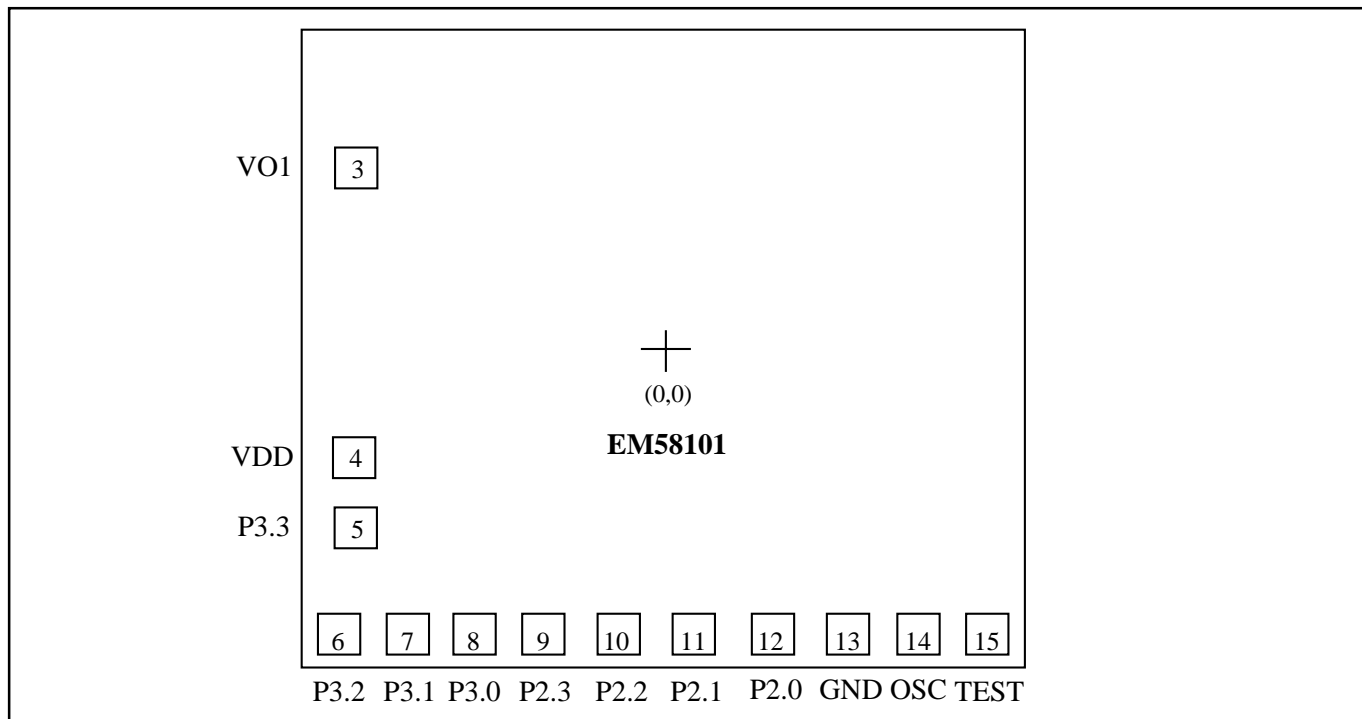


Chip Size : 1300 x 1500 um

For PCB layout, IC substrate must be connected to Vss.

Pad No.	Symbol	X	Y
1	NC		
2	NC		
3	VO1	-402.0	421.4
4	VDD	-418.4	-125.4
5	P3.3	-418.4	-269.3
6	P3.2	-440.4	-523.4
7	P3.1	-318.8	-523.4
8	P3.0	-198.2	-523.4
9	P2.3	-76.1	-523.4
10	P2.2	46.3	-523.4
11	NC		
12	NC		
13	GND	190.5	-523.4
14	OSC	321.5	-523.4
15	TEST	442.7	-523.4
16	NC		
17	NC		
18	NC		
19	NC		
20	NC		

PAD DIAGRAM

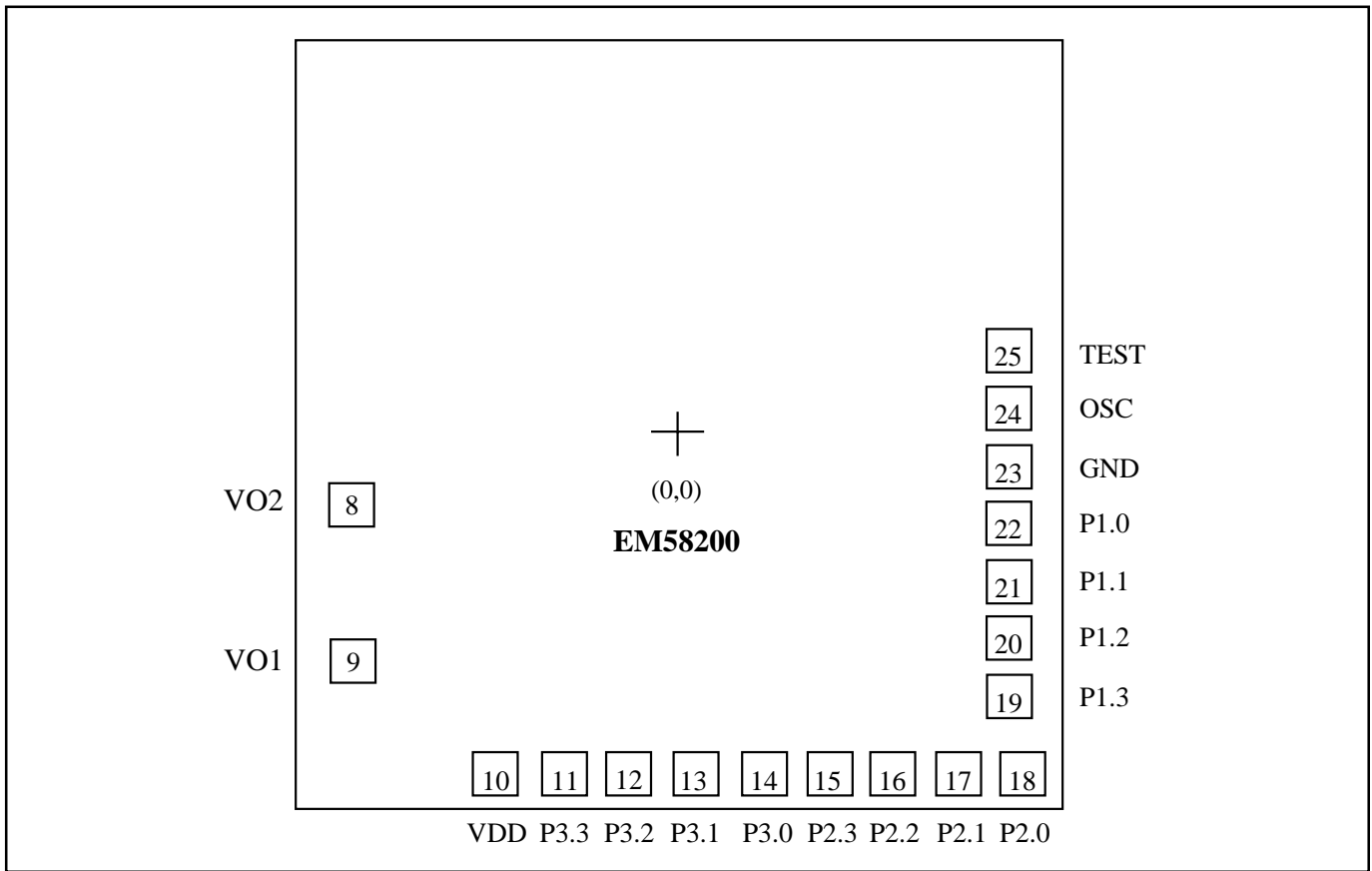


Chip Size : 1500 x 1400 um

For PCB layout, IC substrate must be connected to Vss.

Pad No.	Symbol	X	Y
1	NC		
2	NC		
3	VO1	-512.0	391.0
4	VDD	-528.4	-153.7
5	P3.3	-528.4	-284.7
6	P3.2	-564.8	-498.4
7	P3.1	-443.9	-498.4
8	P3.0	-323.0	-498.4
9	P2.3	-200.9	-498.4
10	P2.2	-78.5	-498.4
11	P2.1	43.9	-498.4
12	P2.0	166.3	-498.4
13	GND	310.5	-498.4
14	OSC	441.5	-498.4
15	TEST	562.7	-498.4
16	NC		
17	NC		
18	NC		
19	NC		
20	NC		

PADDIAGRAM



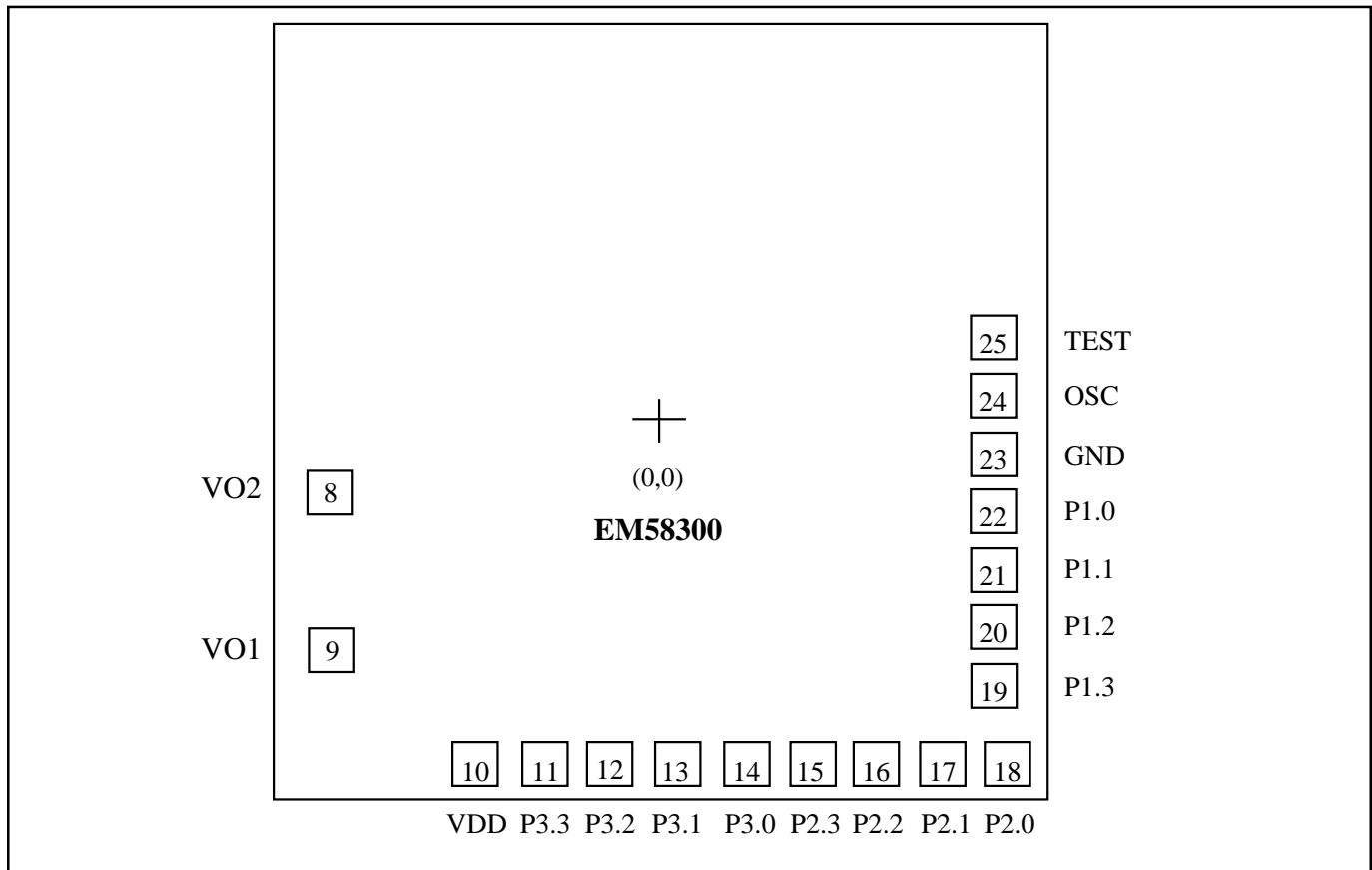
Chip Size : 1700 x 1750 um

For PCB layout, IC substrate must be connected to Vss.

Pad No.	Symbol	X	Y
1	NC		
2	NC		
3	NC		
4	NC		
5	NC		
6	NC		
7	NC		
8	VO2	-572.0	-17.2
9	VO1	-572.0	-401.5
10	VDD	-383.4	-628.4
11	P3.3	-252.4	-628.4
12	P3.2	-131.5	-628.4
13	P3.1	-10.6	-628.4
14	P3.0	110.3	-628.4

Pad No.	Symbol	X	Y
15	P2.3	232.4	-628.4
16	P2.2	354.8	-628.4
17	P2.1	477.2	-628.4
18	P2.0	599.6	-628.4
19	P1.3	588.4	-453.7
20	P1.2	588.4	-331.3
21	P1.1	588.4	-208.9
22	P1.0	588.4	-86.5
23	GND	588.4	57.7
24	OSC	588.4	188.7
25	TEST	588.4	309.9
26	NC		
27	NC		
28	NC		

PAD DIAGRAM



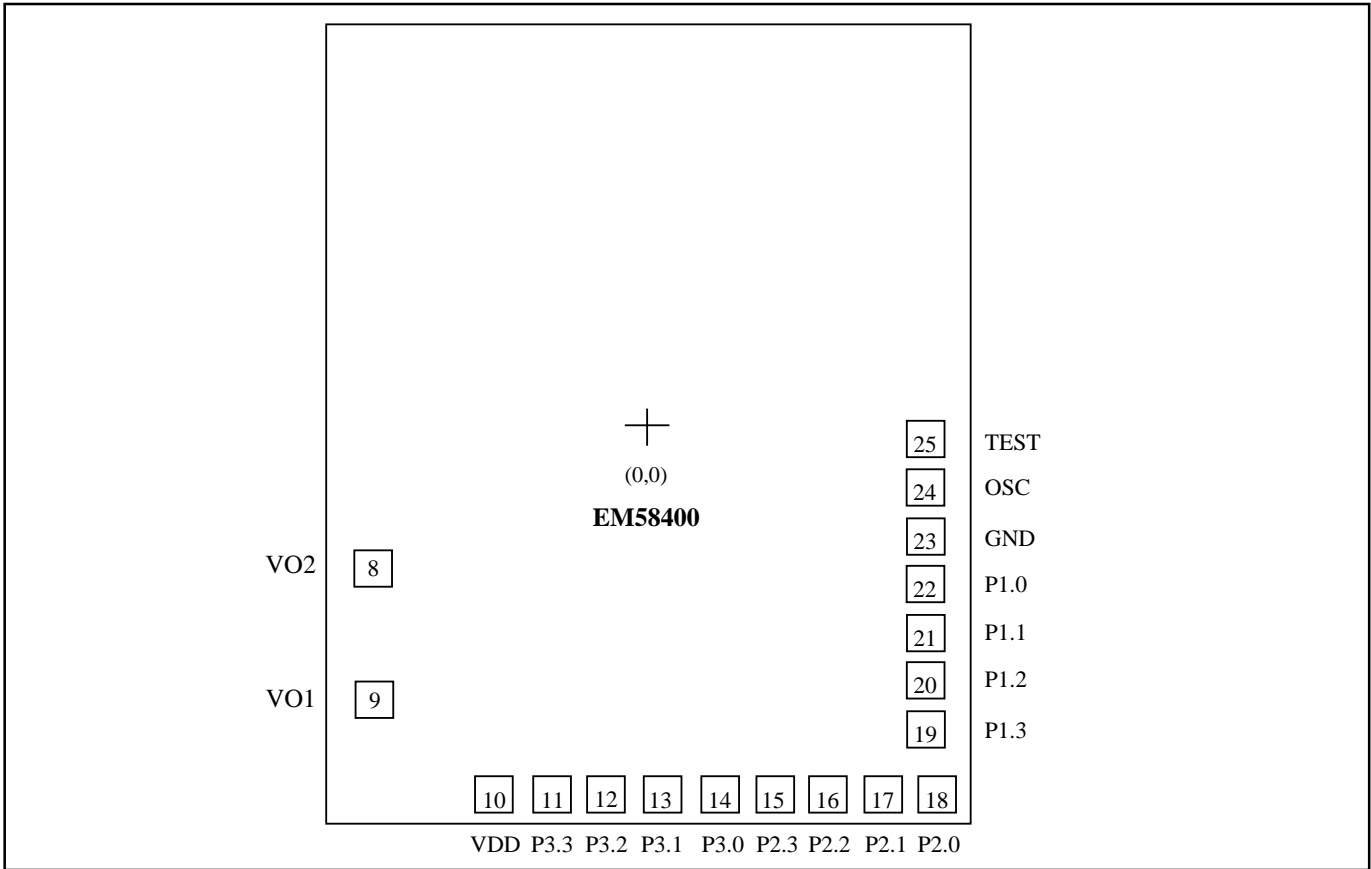
Chip Size : 1700 x 2000 um

For PCB layout, IC substrate must be connected to Vss.

Pad No.	Symbol	X	Y
1	NC		
2	NC		
3	NC		
4	NC		
5	NC		
6	NC		
7	NC		
8	VO2	-572.0	-147.2
9	VO1	-572.0	-531.6
10	VDD	-383.4	-758.4
11	P3.3	-252.4	-758.4
12	P3.2	-131.5	-758.4
13	P3.1	-10.6	-758.4
14	P3.0	110.3	-758.4

Pad No.	Symbol	X	Y
15	P2.3	232.4	-758.4
16	P2.2	354.8	-758.4
17	P2.1	477.2	-758.4
18	P2.0	599.6	-758.4
19	P1.3	588.4	-583.7
20	P1.2	588.4	-461.3
21	P1.1	588.4	-338.9
22	P1.0	588.4	-216.5
23	GND	588.4	-72.3
24	OSC	588.4	58.7
25	TEST	588.4	179.9
26	NC		
27	NC		
28	NC		

PAD DIAGRAM



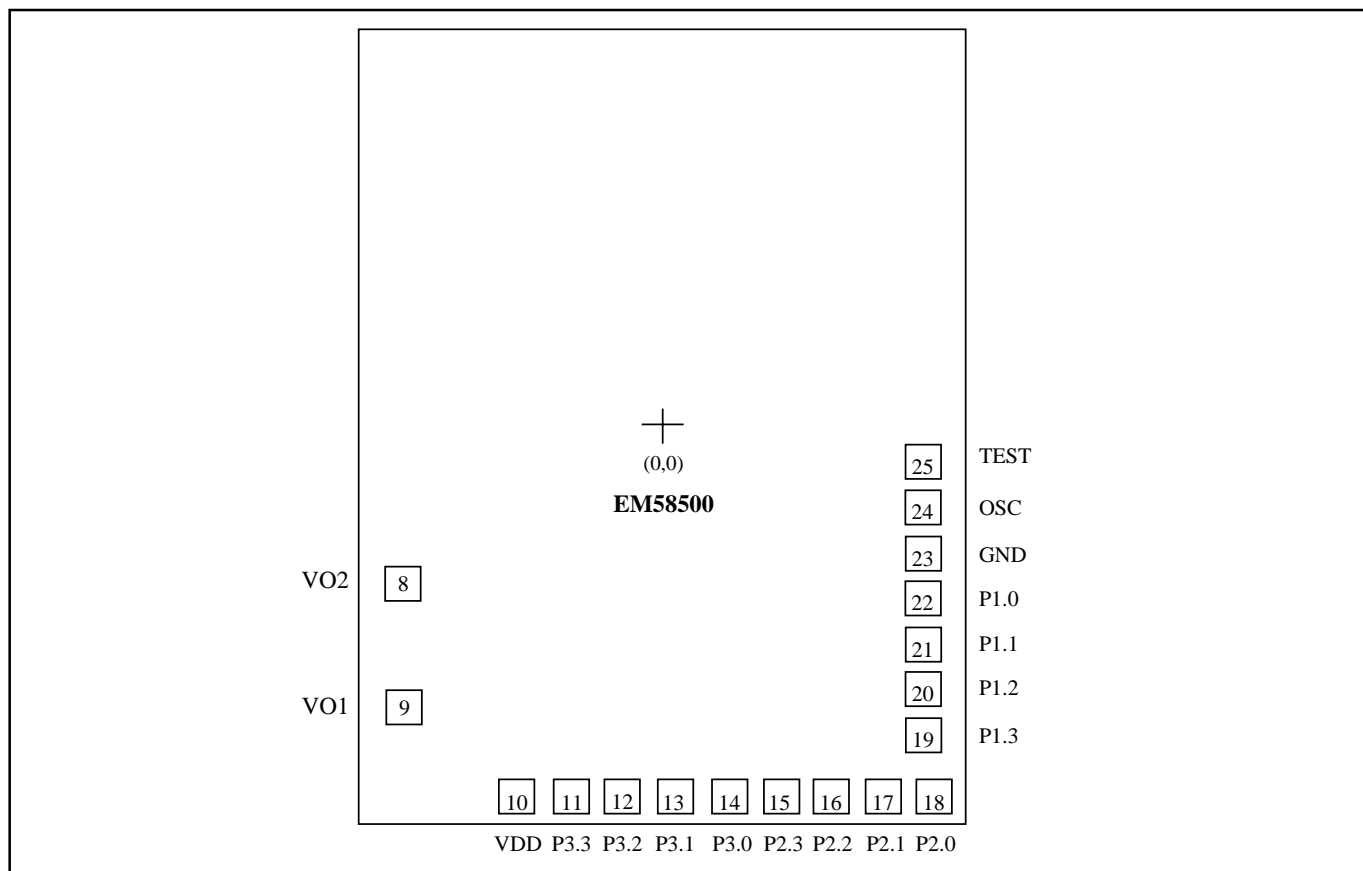
Chip Size : 1700 x 2500 um

For PCB layout, IC substrate must be connected to Vss.

Pad No.	Symbol	X	Y
1	NC		
2	NC		
3	NC		
4	NC		
5	NC		
6	NC		
7	NC		
8	VO2	-572.0	-412.2
9	VO1	-572.0	-796.5
10	VDD	-383.4	-1023.4
11	P3.3	-252.4	-1023.4
12	P3.2	-131.5	-1023.4
13	P3.1	-10.6	-1023.4
14	P3.0	110.3	-1023.4

Pad No.	Symbol	X	Y
15	P2.3	232.4	-1023.4
16	P2.2	354.8	-1023.4
17	P2.1	477.2	-1023.4
18	P2.0	599.6	-1023.4
19	P1.3	588.4	-848.7
20	P1.2	588.4	-726.3
21	P1.1	588.4	-603.9
22	P1.0	588.4	-481.5
23	GND	588.4	-337.3
24	OSC	588.4	-206.3
25	TEST	588.4	-85.1
26	NC		
27	NC		
28	NC		

PADDIAGRAM



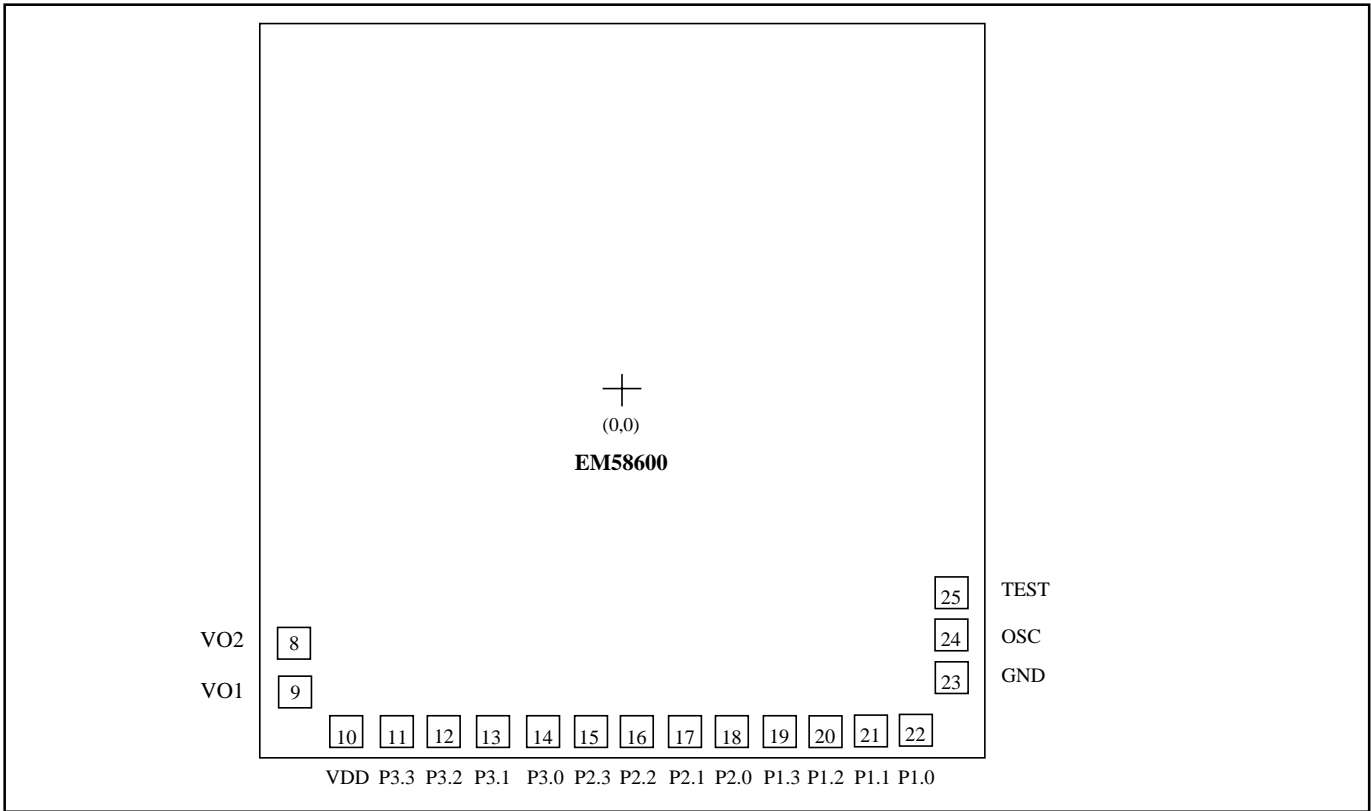
Chip Size : 1700 x 3600 um

For PCB layout, IC substrate must be connected to Vss.

Pad No.	Symbol	X	Y
1	NC		
2	NC		
3	NC		
4	NC		
5	NC		
6	NC		
7	NC		
8	VO2	-572.0	-932.2
9	VO1	-572.0	-1316.6
10	VDD	-383.4	-1543.4
11	P3.3	-252.4	-1543.4
12	P3.2	-131.5	-1543.4
13	P3.1	-10.6	-1543.4
14	P3.0	110.3	-1543.4

Pad No.	Symbol	X	Y
15	P2.3	232.4	-1543.4
16	P2.2	354.8	-1543.4
17	P2.1	477.2	-1543.4
18	P2.0	599.6	-1543.4
19	P1.3	588.4	-1368.7
20	P1.2	588.4	-1246.3
21	P1.1	588.4	-1123.9
22	P1.0	588.4	-1001.5
23	GND	588.4	-857.3
24	OSC	588.4	-726.3
25	TEST	588.4	-605.1
26	NC		
27	NC		
28	NC		

PAD DIAGRAM



Chip Size : 3050 x 3100 um

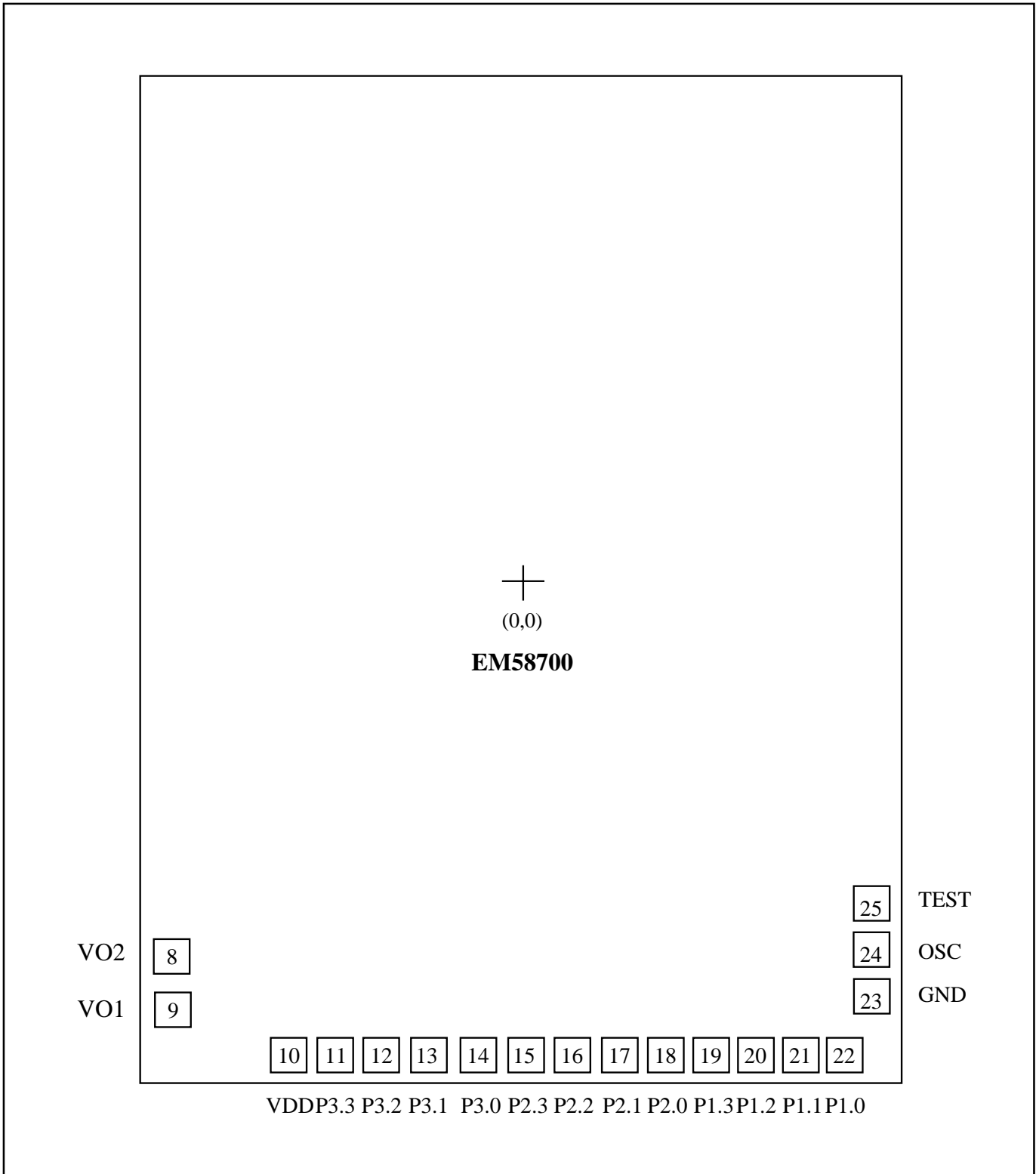
For PCB layout, IC substrate must be connected to Vss.

Pad No.	Symbol	X	Y
1	NC		
2	NC		
3	NC		
4	NC		
5	NC		
6	NC		
7	NC		
8	VO2	-1285.0	-1111.6
9	VO1	-1285.0	-1241.6
10	VDD	-884.3	-1340.0
11	P3.3	-695.7	-1340.0
12	P3.2	-519.2	-1340.0
13	P3.1	-342.7	-1340.0
14	P3.0	-166.2	-1340.0
15	P2.3	15.0	-1340.0
16	P2.2	191.5	-1340.0

Pad No.	Symbol	X	Y
17	P2.1	377.4	-1340.0
18	P2.0	553.9	-1340.0
19	P1.3	739.8	-1340.0
20	P1.2	916.3	-1340.0
21	P1.1	1102.2	-1340.0
22	P1.0	1278.7	-1340.0
23	GND	1293.4	-1138.0
24	OSC	1293.4	-1007.0
25	TEST	1293.4	-885.8
26	NC		
27	NC		
28	NC		
29	NC		
30	NC		
31	NC		
32	NC		

* This specification are subject to be changed without notice.

PAD DIAGRAM



Chip Size : 2930 x 5080 um

For PCB layout, IC substrate must be connected to Vss.

Pad No.	Symbol	X	Y
1	NC		
2	NC		
3	NC		
4	NC		
5	NC		
6	NC		
7	NC		
8	VO2	-1285.0	-2161.6
9	VO1	-1285.0	-2291.6
10	VDD	-884.3	-2390.0
11	P3.3	-695.7	-2390.0
12	P3.2	-519.2	-2390.0
13	P3.1	-342.7	-2390.0
14	P3.0	-166.2	-2390.0
15	P2.3	15.0	-2390.0
16	P2.2	191.5	-2390.0

Pad No.	Symbol	X	Y
17	P2.1	377.4	-2390.0
18	P2.0	553.9	-2390.0
19	P1.3	739.8	-2390.0
20	P1.2	916.3	-2390.0
21	P1.1	1102.2	-2390.0
22	P1.0	1278.7	-2390.0
23	GND	1293.4	-2188.0
24	OSC	1293.4	-2057.0
25	TEST	1293.4	-1935.8
26	NC		
27	NC		
28	NC		
29	NC		
30	NC		
31	NC		
32	NC		